



Rev. 5-1/20/92

			Effective March 7, 19
DECLARATIO	N AND POWER OF ATTORN	EY FOR U.S. PATE	NT APPLICATIONS
(X) Original	() Supplemental () S	Substitute () PC	T () DESIGN
ever to my manne; that I well	or, I hereby declare that: my reside ly believe that I am the original, f inventor (if plural inventors are n on the invention entitled:	arst and sale inventor t	if only one name is like I to
ritle: SEMICONDUCT METHOD, SEM FABRICATING	OR ELEMENT, SEMIC MICONDUCTOR DEVICE METHOD	ONDUCTOR ELE	MENT FABRICATING
of which is described and cla X) the attached specification in the	aimed in: on, or		
and with amendments	ne application Serial No	(if applic	able)
) the specification in In	atternational Application No. PCI	7	C:1
hereby state that I have revi	ewed and understand the content of	Seha abana ida aici d	(it applicable
s amended by any amendm	ent(s) referred to above.	or the above-identified s	pecification, including the claim
acknowledge my duty to dis ion in accordance with Title	sclose information of which I am as e 37, Code of Federal regulations,	ware which is material (§1.56(a).	o the examination of this applic
sesign) of any toreign apping	ty benefits under Title 35, United ation(s) for patent or inventor's ce or inventor's certificate having a fi	ertificate listed below a	ad have also idensified below as
COUNTRY	APPLICATION NO.	DATE OF F	ILING PRIORITY
Japan	8-260645	Oct. 1, 1	996 (x) YES () N
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	8-289836	Oct. 31.	1996 (x) YES () N
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	V	Oct. 31,	() YES () N
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hereby claim the benefit unconsofar as the subject matter of the manner provided by the naterial information as define of the prior application and the SERIAL NO. And I hereby appoint John Tours, 154; Jeffrey Nolton, Reg. Notatles R. Watta, Reg. 33,142;	ler Title 35, United States Code, § f each of the claims of this applicati e first paragraph of Title 35, Unite d in Title 37, Code of Federal Regu he national or PCT international U.S. FH.ING DATE . Miller, Reg. No. 21,120; Michael b. 25,408; Warren M. Cheek, Jr., R who together constitute the firm of M	OCE. 31, 120 of any United State on is not disclosed in the d States Code, §112, I a stations, §1.56(a) which filing date of this appl () Patented (() Patented (() Patented (() R. Davis, Reg. No. 25, I eg. No. 33,367; Nils E.	() YES () N () YES () N () YES () No
hereby claim the benefit unconsofar as the subject matter of the manner provided by the naterial information as define of the prior application and the SERIAL NO. And I hereby appoint John Township Jeffrey Nolton, Reg. Notatles R. Watts, Reg. 33,142; orneys to prosecute this application of the U.S. at the prior authorize the U.S. at the prior auth	ler Title 35, United States Code, § f each of the claims of this applicati e first paragraph of Title 35, Unite d in Title 37, Code of Federal Regu he national or PCT international U.S. FILING DATE . Miller, Reg. No. 21,120; Michael 15, 25,408; Warren M. Cheek, Ir. R	OCT. 31, 120 of any United States on is not disclosed in the disclosed in the distance of this applications, \$1.56(a) which filing date of this application of the distance o	() YES () No

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persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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The above application may be more particularly identified as follows:

U. S. Application Serial No	riling Date
Applicant Reference Number	Atty Docket No
Title of Invention METHOD; SEMICONDUCTOR I	SEMICONDUCTOR ELEMENT FABRICATING DEVICE, AND SEMICONDUCTOR DEVICE
FABRICATING METHOD	